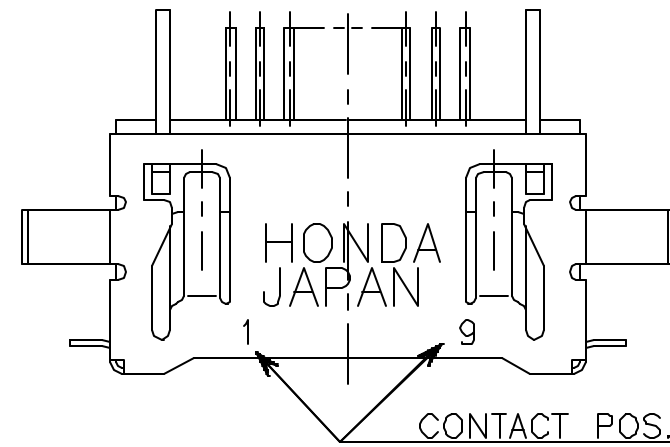




NOTE 1.CONTACT PLATING
Au(0.1μm MIN.) OVER
Pd/Ni(1μm MIN.) ON MATING AREA,
TIN/LEAD ON TERMINATION AREA,
ALL OVER NICKEL UNDERPLATED.

2.COPLANARITY OF SMT TERMINAL
IS 0 ±0.05 mm

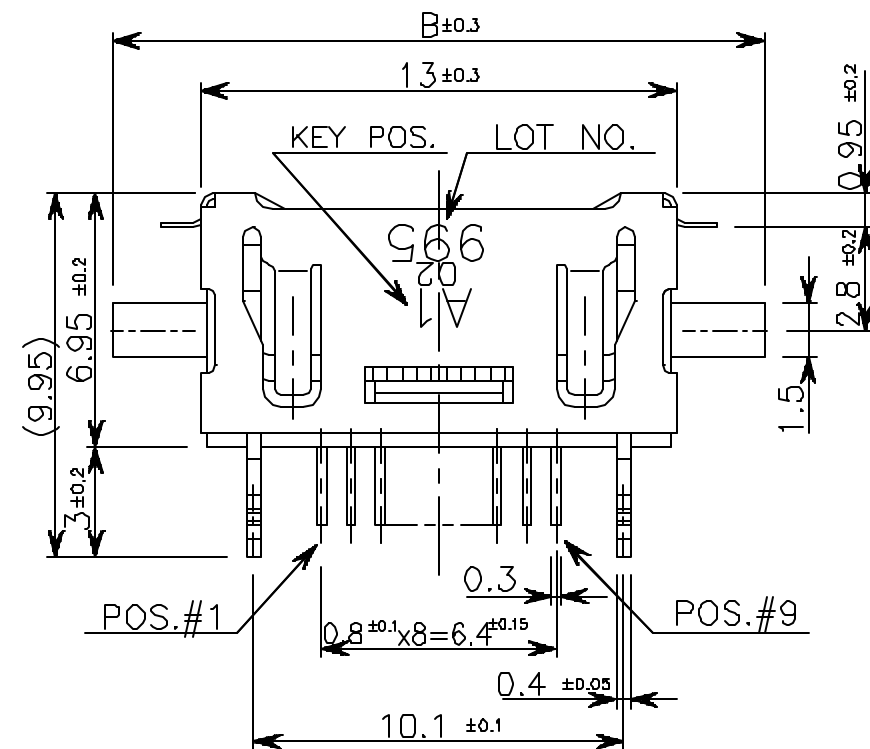
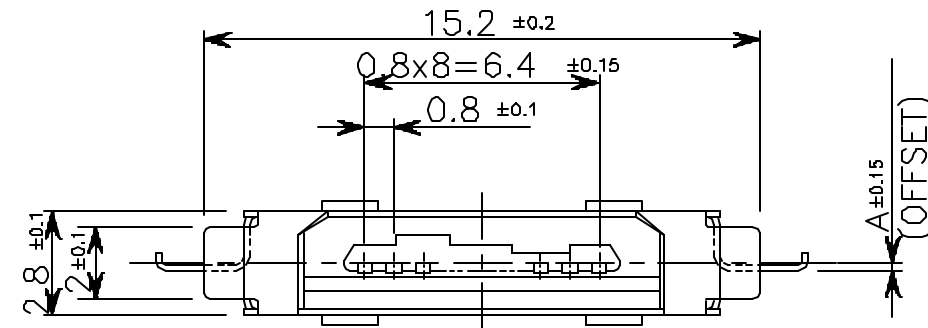
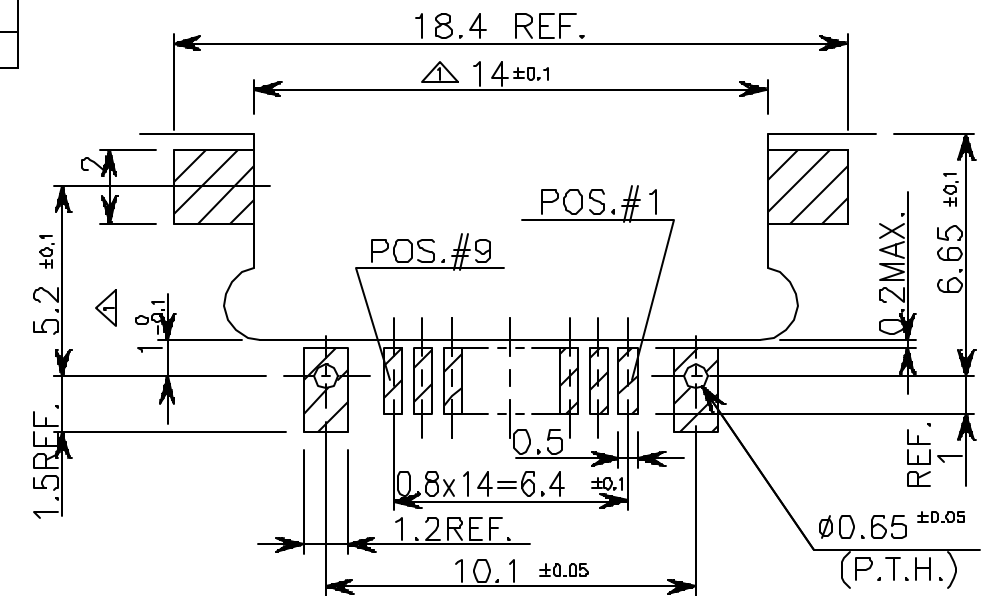
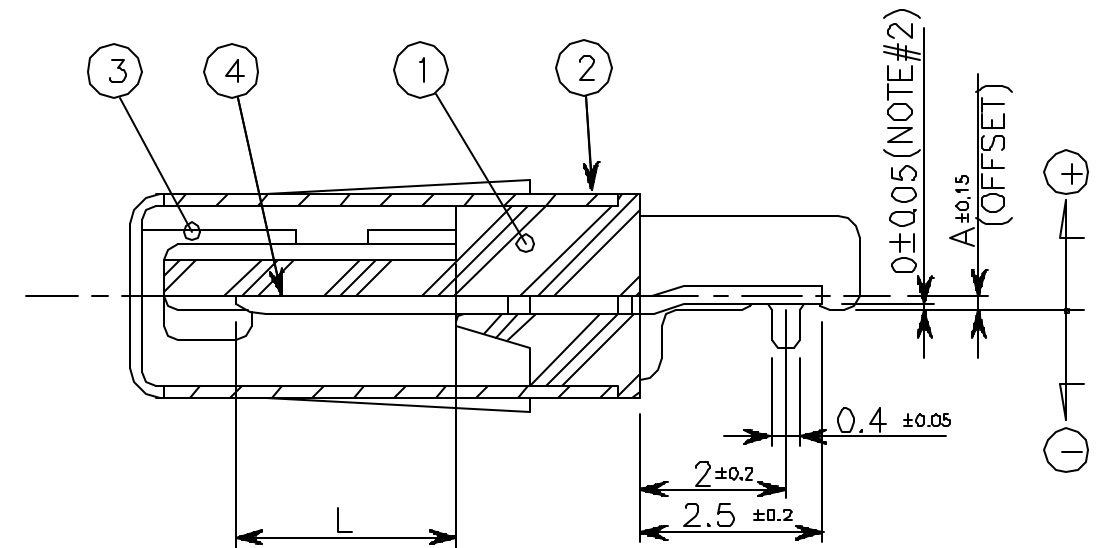
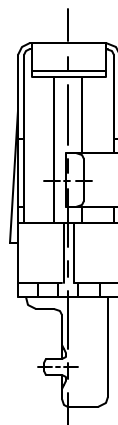
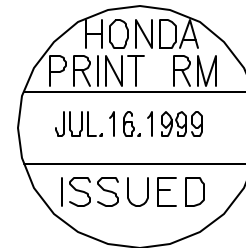


TABLE-2

P/N	A OFFSET	B DIM.	P.C.B. THICKNESS
RMC-E9M2Y-OM02-MA()	0.2	17.8	0.5
*RMC-E9M2Y-OM03-MA()	0.3	17.6	0.5
*RMC-E9M2Y-OM05-MA()	0.5	17.2	0.5
*RMC-E9M2Y-OM06-MA()	0.6	17.0	0.5
*RMC-E9M2Y-OM08-MA()	0.8	16.6	0.4

*:THIER CONFIGURATIONS ARE IN THE PLANING STAGE



RECOMMENDED P.C.B LAYOUT(5/1)

(CONN. MOUNT SIDE) t=REFER TO TABLE-2

TABLE-1

P/N	KEY POS.	MARKING (KEY POS.)	APPLICABLE CONNECTOR
RMC-E9M2Y-OM()-MA2	2	A2	RMC-E9FS-BSLA()N-MA1 RMC-E9F2S-BSLA()N-MA1 AND OTHERS
RMC-E9M2Y-OM()-MA1	1	A1	RMC-E9FS-BSLA()N-MA2 RMC-E9F2S-BSLA()N-MA2 AND OTHERS
RMC-E9M2Y-OM()-MA	NOTHING	A	RMC-E9FS-BSLA()N-MA() RMC-E9F2S-BSLA()N-MA() AND OTHERS

				4	CONTACT	PHOSPHOR BRONZE	9	NOTE#1	_____
△				3	LOCKING DEVICE	STAINLESS STEEL	2		_____
△	JUL 14 1999	K.Y	ADD. OFF SET 0.5mm	2	SHELL	STAINLESS STEEL	1		_____
△	MAY 28 1999	K.Y	CHANGE P.C.B. DIM.	1	INSULATOR	PPS(GF)	1		UL94V-0 BLACK
LTR.	DATE	BY	REV. DESCRIPT	NO.	PART NAME	MATERIAL	QTY	FINISH	NOTE
DATE MAY.10(1999)		SCALE 5 / 1		UNIT mm(INCH) 3RD A.P.		HONDA TSUSHIN KOGYO., LTD.			
DR		DE		CHK		NAME		RMC SERIES BOARD SIDE SHIELDED I/O CONNECTOR FOR CF CARD (9POS.,0.8mmPITCH,SMT TERMINATION TYPE)	
						PART NO.		RMC-E9M2Y-OM()-MA()	REV. 2B